

Session Title:	[WB2] Advanced CMP Process II
Session Date:	November 16 (Wed.), 2022
Session Time:	13:30-15:00
Session Room:	Room B (Grand Ballroom 1, 2F)
Session Chair:	Prof. Jeagun Park (Hanyang Univ., Korea)

[WB2-1] [Invited] 13:30-14:00

Hybrid CMP Slurry Supply Using Ionization and Atomization

Hoseung Jo, Dasol Lee (Pusan Nat'l Univ., Korea), Hyunseop Lee (Dong-A Univ., Korea), and Haedo Jeong (Pusan Nat'l Univ., Korea)

[WB2-2] 14:00-14:20

Application on CMP Process of Large Size OLED LTPS Thin Film Using OSCAR Type Polisher

Gwoon Shim, Hyuntaek Lee, and Jongkook Song (SC Plat Co., Ltd., Korea)

[WB2-3] 14:20-14:40

Silicon Wafer Preparation for Semiconductor Devices: Surface Defects

Eunsuck Choi and Chanmin Jung (SK siltron, Korea)

[WB2-4] 14:40-15:00

Formation Mechanism of Asperity and Its Effect based on Pore Size in Chemical Mechanical Planarization

Sanghuck Jeon, Yuna Nam, Minwoo Kang, Kihong Park, and Taesung Kim (Sungkyunkwan Univ., Korea)